

**ABSTRACT**

An electronic component includes at least one semiconductor chip, which has an active chip top side with contact areas and has a chip rear side arranged on a carrier top side of a circuit carrier. The circuit carrier and the chip top side are covered by a common  
5 rewiring layer having external contact areas at a different level. The different level is matched to a common level of external contact top sides by means of different heights of in part compliant external contacts.